

| L Number | Hits  | Search Text   | DB                         | Time stamp       |
|----------|-------|---|----------------------------|------------------|
| 8        | 1180  | (tetramethylammo\$4 \$methlyammonium tetra\$ammonium) and ("CMP" "cmp" polish\$3)   | USPAT                      | 2003/01/16 14:52 |
| 9        | 34    | (tetramethylammo\$4 \$methlyammonium tetra\$ammonium) and ("CMP" "cmp" polish\$3)   | EPO; JPO; DERWENT; IBM_TDB | 2003/01/16 14:53 |
| 10       | 293   | (tetramethylammo\$4 \$methlyammonium tetra\$ammonium) and ("CMP" "cmp" polish\$3)   | US-PGPUB                   | 2003/01/16 14:53 |
| 11       | 2915  | (polish\$3 "CMP" "cmp") and rough\$6 and (substrate wafer)  | US-PGPUB                   | 2003/01/16 14:58 |
| 12       | 11816 | (polish\$3 "CMP" "cmp") and rough\$6 and (substrate wafer)  | USPAT                      | 2003/01/16 14:56 |
| 13       | 8421  | ((polish\$3 "CMP" "cmp") and rough\$6 and (substrate wafer)) and (rough\$6 same (substrate wafer layer film))   | USPAT                      | 2003/01/16 14:58 |
| 14       | 1675  | ( ((polish\$3 "CMP" "cmp") and rough\$6 and (substrate wafer)) and (rough\$6 same (substrate wafer layer film))) and (rough\$6 adj2 (substrate wafer layer film)) | USPAT                      | 2003/01/16 14:58 |
| 15       | 2013  | (polish\$3 "CMP" "cmp") and rough\$6 and (substrate wafer)  | EPO; JPO; DERWENT; IBM_TDB | 2003/01/16 14:59 |
| 16       | 1684  | ((polish\$3 "CMP" "cmp") and rough\$6 and (substrate wafer)) and (rough\$6 same (substrate wafer))  | EPO; JPO; DERWENT; IBM_TDB | 2003/01/16 15:00 |
| -        | 0     | hans-walitzki.in. howard-hogle.in. wing-luk.in. claudian-nicolesco.in.  | USPAT                      | 2003/01/16 13:41 |
| -        | 0     | hans-walitzki.in. howard-hogle.in. wing-luk.in. claudian-nicolesco.in.  | US-PGPUB                   | 2003/01/14 18:01 |
| -        | 0     | hans-walitzki.in. howard-hogle.in. wing-luk.in. claudian-nicolesco.in.  | EPO; JPO; DERWENT; IBM_TDB | 2003/01/14 18:01 |
| -        | 517   | 438/690,691.ccls.   | USPAT                      | 2003/01/14 18:03 |
| -        | 1379  | 438/692,693.ccls.   | USPAT                      | 2003/01/14 18:03 |
| -        | 815   | 438/694,695.ccls.   | USPAT                      | 2003/01/14 18:03 |
| -        | 569   | 438/697,699.ccls.   | USPAT                      | 2003/01/14 18:05 |
| -        | 225   | 438/964.ccls.   | USPAT                      | 2003/01/14 18:06 |
| -        | 288   | 438/974.ccls.   | USPAT                      | 2003/01/14 18:06 |
| -        | 463   | 438/977.ccls.   | USPAT                      | 2003/01/14 18:07 |
| -        | 428   | 438/459.ccls.   | USPAT                      | 2003/01/14 18:07 |
| -        | 1108  | 438/460,464,465,455.ccls.   | USPAT                      | 2003/01/14 18:11 |

|   |       |  |       |                     |
|---|-------|--|-------|---------------------|
| - | 11149 | (tetramethylammo\$4 \$methlyammonium<br>tetra\$ammonium \$ammonium) and ("CMP"<br>"cmp" polish\$3) | USPAT | 2003/01/16<br>14:52 |
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## Results:

Journal or Magazine = **JNL** Conference = **CNF** Standard = **STD****1 A statistical polishing pad model for chemical-mechanical polishing***Tat-Kwan Yu; Yu, C.C.; Orlowski, M.;*

Electron Devices Meeting, 1993. Technical Digest., International , 5-8 Dec 1993

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[\[Abstract\]](#) [\[PDF Full-Text \(284 KB\)\]](#) **IEEE CNF****2 Bonding of thin films on 200 mm silicon wafers using chemical mechanical polishing***Jones, E.C.; Tiwari, S.; Chan, K.K.; Solomon, P.M.; Power, M.;*

SOI Conference, 1998. Proceedings., 1998 IEEE International , 5-8 Oct 1998

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[\[Abstract\]](#) [\[PDF Full-Text \(296 KB\)\]](#) **IEEE CNF****3 Morphology and adhesion strength in electroless Cu metallized AlN substrate***Chang, J.H.; Duh, J.G.; Chiou, B.S.;*

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A Volume: 16 Issue: 8 , Dec 1993

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[\[Abstract\]](#) [\[PDF Full-Text \(812 KB\)\]](#) **IEEE JRN****4 Material removal mechanism in chemical mechanical polishing: theoretical modeling***Jianfeng Luo; Dornfeld, D.A.;*